### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4009273

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
KAZUAKI KOZASA	06/27/2016
SYUNYA KOBUCHI	06/27/2016
KATSUHISA SUGIMORI	06/27/2016

### **RECEIVING PARTY DATA**

Name:	SUMCO CORPORATION	
Street Address:	1-2-1, SHIBAURA, MINATO-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	105-8634	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15119260

### **CORRESPONDENCE DATA**

**Fax Number:** (703)716-1180

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 703-716-1191

**Email:** gbpatent@gbpatent.com

Correspondent Name: GREENBLUM & BERNSTEIN, P.L.C. Address Line 1: 1950 ROLAND CLARKE PLACE

Address Line 4: RESTON, VIRGINIA 20191

ATTORNEY DOCKET NUMBER:	P50746	
NAME OF SUBMITTER:	DANIEL B. MOON	
SIGNATURE:	/Daniel B. Moon/	
DATE SIGNED:	08/16/2016	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

### **Total Attachments: 5**

source=P50746\_Assign#page1.tif source=P50746\_Assign#page2.tif source=P50746\_Assign#page3.tif

PATENT 503962618 REEL: 039457 FRAME: 0116

source=P50746\_Assign#page4.tif source=P50746\_Assign#page5.tif

> PATENT REEL: 039457 FRAME: 0117

# COMBINED INVENTOR'S DECLARATION AND ASSIGNMENT

### **DECLARATION**

The herein-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

# Authorization to Permit Access to Application by Participating Office

Patent Office (EPO), the Japan Patent Office (JPO), the Korean Intellectual Property Office (KIPO), the World Intellectual Property Office (WIPO), and any other intellectual property offices in which a foreign application claiming priority to the herein-identified patent application is filed access to the herein-identified patent application. See 37 CFR 1.14(c) and (h). This box should not be checked if the applicant does not wish the EPO, JPO, KIPO, WIPO, or other intellectual property office in which a foreign application claiming priority to the herein-identified patent application is filed to have access to the herein-identified patent application.

In accordance with 37 CFR 1.14(h)(3), access will be provided to a copy of the herein-identified patent application with respect to: 1) the herein-identified patent application-as-filed; 2) any foreign application to which the herein-identified patent application claims priority under 35 U.S.C. 119(a)-(d) if a copy of the foreign application that satisfies the certified copy requirement of 37 CFR 1.55 has been filed in the herein-identified patent application; and 3) any U.S. application-as-filed from which benefit is sought in the herein-identified patent application.

In accordance with 37 CFR 1.14(c), access may be provided to information concerning the date of filing the Authorization to Permit Access to Application by Participating Offices.

Direct Correspondence to: CUSTOMER NUMBER 07055

At: Greenblum & Bernstein, P.L.C. 1950 Roland Clarke Place Reston, VA 20191

Direct Telephone Calls to: Greenblum & Bernstein, P.L.C. (703) 716-1191

PATENT REEL: 039457 FRAME: 0118

### **ASSIGNMENT**

WHEREAS, **Kazuaki KOZASA**, a resident of Minato-ku, Tokyo, whose mailing address is c/o SUMCO CORPORATION 1-2-1, Shibaura, Minato-ku, Tokyo 105-8634, Japan, **Syunya KOBUCHI**, a resident of Minato-ku, Tokyo, whose mailing address is c/o SUMCO CORPORATION 1-2-1, Shibaura, Minato-ku, Tokyo 105-8634, Japan, and **Katsuhisa SUGIMORI**, a resident of Minato-ku, Tokyo, whose mailing address is c/o SUMCO CORPORATION 1-2-1, Shibaura, Minato-ku, Tokyo 105-8634, Japan, hereinafter referred to as the ASSIGNORS, have invented a certain improvement relating to

## METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER

for which they have jointly executed an application for Letters Patent of the United States to be filed in the United States Patent and Trademark Office.

AND WHEREAS, **SUMCO CORPORATION**, a corporation organized and existing under the laws of Japan, whose mailing address is 1-2-1, Shibaura, Minato-ku, Tokyo 105-8634, Japan, hereinafter known as the ASSIGNEE, is desirous of acquiring the entire right, title and interest for the United States and elsewhere throughout the world in and to said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues, reexaminations, and prolongations thereof.

NOW, THIS WITNESSETH that for good and valuable consideration, the receipt whereof is hereby acknowledged, said ASSIGNORS hereby assign, sell and transfer to said ASSIGNEE, its assigns and legal representatives, the entire and exclusive right, title and interest in and to said invention and application, for the United States and elsewhere throughout the world including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted therefor and all rights to sue for past and future infringement thereunder, said ASSIGNEE and its assigns and legal representatives to have, hold, exercise and enjoy the said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues, reexaminations and prolongations thereof, with all the rights, powers, privileges, and advantages in any ways arising from or pertaining thereto, for and during the term or terms of any and all such Letters Patent when

PATENT REEL: 039457 FRAME: 0119 granted, including any and all renewals, reissues, reexaminations, and prolongations thereof, for the use and benefit of said ASSIGNEE and its assigns and legal representatives in as ample and beneficial a manner to all intents and purposes as the said ASSIGNORS might or could have held and enjoyed the same, if this assignment had not been made.

AND said ASSIGNORS hereby agree to execute all papers necessary to file applications in the United States and elsewhere throughout the world for said invention and to assign the same to said ASSIGNEE, or any assignee acquiring title to said invention, and to execute any other papers that may be needed in connection with filing said application and securing Letters Patent thereon.

AND said ASSIGNORS authorize and request the Commissioner of Patents to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said ASSIGNEE, its assigns and legal representatives, in accordance herewith.

IN TESTIMONY WHEREOF, this assignment is executed by said ASSIGNORS, on the respective dates indicated below.

First Witness:	
(Name)	
(Date)	
	Kazuski Kozasa
	Kazuaki KOZASA
Second Witness:	6.27.20/6 Date
(Name)	
(Date)	

{01536834.DOC}

First Witness:	
(Name)	
(Date)	
	Syunya Hobuchi
	Syunya KOBUCHI
	6.27.2016
Second Witness:	Date
(Name)	
(Date)	

First Witness:	
(Name)	
(Date)	
	Katsuhisa Sugimori
	Katsuhisa SUGIMORI
	6.27.2016
Second Witness:	Date
(Name)	
Date)	

{01536834.DOC}